

Glass Substrate Report

for Advanced Semiconductor Packages

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- This Report Focuses on Glass Substrates for Advanced Semiconductor Packages
- Market & Technology Study of Glass Substrates by Product Stage.
 - * Product Stage : Plane Glass/TGV Glass Substrate/Metalized TGV Glass Substrate/
Glass Core FCBGA Substrates/Glass Interposers
 - * Market Study : Market Scale Forecast (2024-2035, Volume/Value)
 - * Technology Study : Comparative Analysis of Various Construction Methods (TGV/Metalizing)
Technology Roadmap of Glass Core FCBGA & Glass interposer
- Case Study of Companies Related to Glass Substrates

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Outline of this research report

1. Purpose

Our goal is to provide you with foundational data for business strategy development in the relevant market by conducting a detailed studies of the technology and market Trends in Glass substrates.

2. Research period

Survey: August-November/2024, Analysis: December 2024- January 2025

3. Research Method

Information gathering: Direct interview or questionnaire, secondary research

4. Object of the Study : Product & Related Companies

- Plane Glass : Corning/NEG/NSG/SCHOTT
- TGV Substrates : AGC/NSC/NICHIWA-MFG/MICRO TECHNOLOGY/LPKF/JNTC/TGV Circuits/etc.,
- Metalized TGV Substrates : DNP/TOPPAN/EBINAX/Koto/NSC/ABSOLICS/Intel
- Glass Core FCBGA & Glass Interposer : IBIDEN/SHINKO/KYOCERA/FICT/SEMCO/UMTC
- Plating Solutions : ATOTECH/OKUNO/UYEMURA/etc.,
- Insulation Layer Materials : AJINOMOTO/ASAHI KASEI/ SUMITOMO BAKELITE/HDM/FFEM/etc.,
- Related Equipment : Mitsubishi Electric/Via Mechanics/GIGAPHOTON/USHIO/CANON/NIKON/ ORC/EBARA/etc.,

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